

R E M A R K S

Reconsideration of this application, as amended, is respectfully requested.

Claim 11 has been amended to correct a minor clerical error. Claim 14 has been amended to more clearly recite the structure and arrangement of the upper conductors, interlayer conductors, and interlayer dielectric layer. And claim 52 has been added to explicitly recite that the upper conductors are provided on the interlayer dielectric layer.

No new matter has been added, and no new issues with respect to patentability have been raised. Accordingly, it is respectfully requested that the amendments to the claims be approved and entered, and it is respectfully submitted that the claims remain in condition for allowance.

If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned for prompt action.

Respectfully submitted,

/Douglas Holtz/

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